

DATA SHEET

SKY85006-11: 2.4 GHz High-Power Wireless LAN Power Amplifier

Applications

- DSSS 2.4 GHz WLAN (IEEE 802.11b)
- OFDM 2.4 GHz WLANs:
 - IEEE 802.11b/g/n
 - 256 QAM IEEE 802.11ac
 - 1024 QAM IEEE 802.11g
- Access points
- PCMCIA cards
- PC cards

Features

- Single 5 V supply operation:
 - +22 dBm, EVM = -43 dB, MCS11
 - +23 dBm, EVM = -35 dB, MCS8
 - +26 dBm, EVM = -30 dB, 802.11g, OFDM 54 Mbps
 - +26 dBm, ACPR < -32 dBc, 802.11b
- Gain: +35 dB
- Integrated temperature-compensated logarithmic power detector
- Digital power amplifier enable pin (VEN)
- Small laminate (20-pin, 3.0 × 4.0 × 0.8 mm) package (MSL3, 260 °C per JEDEC J-STD-020)



Skyworks Green™ products are compliant with all applicable legislation and are halogen-free. For additional information, refer to *Skyworks Definition of Green™*, document number SQ04-0074.

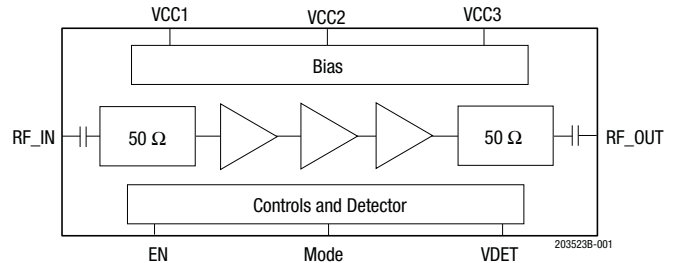


Figure 1. SKY85006-11 Block Diagram

Description

The SKY85006-11 is a 2.4 GHz power amplifier (PA) designed for use in the 2.4 GHz Industrial, Scientific, Medical (ISM) band for wireless local area network (LAN) applications. The SKY85006-11 device incorporates a power detector for closed loop monitoring of the output power.

The SKY85006-11 includes a digital enable for device on/off control. The SKY85006 also includes a MODE pin for use with digital predistortion to save current consumption.

The SKY85006-11 temperature-compensated power detector is highly immune to mismatch at its output, with less than +1.5 dB of variation with a 2:1 mismatch.

A block diagram of the SKY85006-11 is shown in Figure 1. The device package and pinout are shown in Figure 2. Signal pin assignments and functional pin descriptions are described in Table 1.

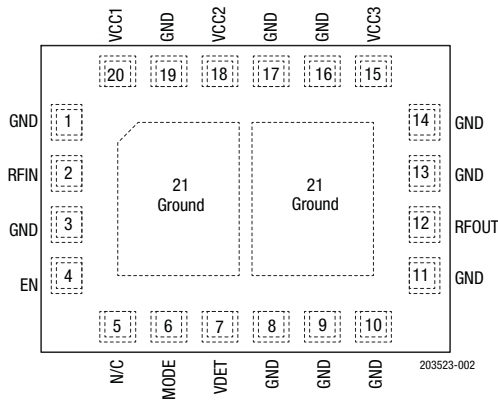


Figure 2. SKY85006-11 Pinout

Table 1. SKY85006-11 Signal Descriptions

Pin	Name	Description	Pin	Name	Description
1	GND	Ground	12	RF_OUT	RF Output
2	RF_IN	RF Input	13	GND	Ground
3	GND	Ground	14	GND	Ground
4	EN	PA enable	15	VCC3	Power supply for third stage
5	N/C	No connect	16	GND	Ground
6	MODE	High-linearity/DPD mode control	17	GND	Ground
7	VDET	Power detector output	18	VCC2	Power supply for second stage
8	GND	Ground	19	GND	Ground
9	GND	Ground	20	VCC1	Power supply for first stage
10	GND	Ground	21	GND	Ground pad
11	GND	Ground			

Electrical and Mechanical Specifications

The absolute maximum ratings of the SKY85006-11 are provided in Table 2. The recommended operating conditions are specified in Table 3.

The electrical specifications are provided in Tables 4 through 8.

Table 2. SKY85006-11 Absolute Maximum Ratings¹

Parameter	Symbol	Minimum	Maximum	Units
Supply voltage	VCC1, VCC2, VCC3	-0.3	+5.5	V
DC input on EN	VIN	-0.3	+3.6	V
RF input power (RF out terminated in 50 Ω)	PIN		+12.0	dBm
Operating temperature range	TA	-40	+85	°C
Junction temperature	TJ		+150	°C
Storage temperature range	TSTG	-40	+150	°C
Electrostatic discharge: Human Body Model (HBM), Class 1C (all pins)	ESD		1500	V

¹ Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

ESD HANDLING: *Although this device is designed to be as robust as possible, electrostatic discharge (ESD) can damage this device. This device must be protected at all times from ESD when handling or transporting. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD handling precautions should be used at all times.*

Table 3. SKY85006-11 Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Units
Ambient temperature	TA	-40	+25	+85	°C
Supply voltage, relative to GND = 0 V	Vcc	3.0	5.0	5.5	V

Table 4. SKY85006-11 Electrical Specifications: DC Characteristics¹

(Vcc = 5.0 V, MODE = 0.0 V, EN = VENH, TA = 25 °C as Measured on the Evaluation Board (De-Embedded to the Device), All Unused Ports are Terminated with 50 Ω, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Supply current (sum of all VCCs)	ICC-802.11b	POUT = +28 dBm		510	550	mA
	ICC-802.11n	POUT = +26 dBm		430	470	mA
	ICC-802.11ac	POUT = +23 dBm		340	370	mA
	ICQ	No RF, MODE = 0 V No RF, MODE = 3.3 V (DPD mode)		210 140		mA mA
Supply current	ICC	VEN = 0 V, No RF			150	µA
Thermal conductivity	θJC				26.5	°C/W

¹ Performance is guaranteed only under the conditions listed in this table.

Table 5. SKY85006-11 Electrical Specifications: AC Characteristics: 802.11g/n/ac Transmit Characteristics¹

(Vcc = 5.0 V, MODE = 0.0 V, EN = 3.3 V, TA = 25 °C as Measured on the Evaluation Board (De-Embedded to the Device), All Unused Ports are Terminated with 50 Ω, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Frequency range	fL-U		2400		2500	MHz
Output power	POUT	MCS10, HT40, -43 dB DEVM	+22	+23		dBm
		MCS10, HT40, -40 dB DEVM	+23	+23.5		dBm
		MCS8, HT40, -35 dB EVM	+23	+24		dBm
		MCS7, HT20, -30 dB EVM	+24	+26		dBm
		802.11b, CCK signal, BT = 0.045, mask	+27	+29		dBm
		MCS0, HT20, mask	+26	+28		dBm
+1 dB output compression point	OP1dB	No modulation	+29	+31		dBm
Out-of-band	OOB	MCS0 to MCS9, HT20. In-band output power at which power in the 2310 to 2390 MHz or 2483 to 2500 MHz restricted bands does not exceed -41.2 dBm/MHz.		+22		dBm
Input return loss	IS11I		10	15		dB
Output return loss	IS22I			6		dB
Small signal gain	IS21I	Pin = -25 dBm	32	35		dB
Gain variation over band	ΔS21	Pin = -25 dBm, fin = 2400 to 2500 MHz	-1.5		+1.5	dB
Harmonics	2f	POUT = 29 dBm, 802.11b, 1 Mbps		-40	-35	dBm/MHz
	3f				-50	dBm/MHz
Rise and fall time	tr, tf				0.5	µs
Stability	STAB	CW, POUT = +29 dBm, 0.1 GHz to 20 GHz, Load VSWR = 4:1	All non-harmonically related outputs < -42 dBm/MHz			
Ruggedness	RUG	Pin = +10 dBm, Load VSWR = 10:1	No damage			

¹ Performance is guaranteed only under the conditions listed in this table.

Table 6. SKY85006-11 Electrical Specifications: AC Characteristics: 802.11g/n/ac Transmit Characteristics¹
(V_{CC} = 3.3 V, MODE = 0.0 V, EN = 3.3 V, T_A = 25 °C as Measured on the Evaluation Board (De-Embedded to the Device), All Unused Ports are Terminated with 50 Ω, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Frequency range	f _{L-U}		2400		2500	MHz
Output power	P _{OUT}	MCS10, HT40, -43 dB EVM MCS8, HT40, -35 dB EVM MCS7, HT20, -30 dB EVM 802.11b, CCK signal, BT = 0.045, mask MCS0, HT20, mask		+19 +21 +22 +26 +26		dBm dBm dBm dBm dBm
+1 dB output compression point	OP1dB	No modulation		+28		dBm
Out-of-band	OOB	MCS0 to MCS9, HT20. In-band output power at which power in the 2310 to 2390 MHz or 2483 to 2500 MHz restricted bands does not exceed -41.2 dBm/MHz.		19		dB
Small signal gain	IS21I	P _{IN} = -25 dBm		34		dB
Gain variation over band	ΔS21	P _{IN} = -25 dBm, f _{IN} = 2400 to 2500 MHz	-1.5		+1.5	dB
Harmonics	2f 3f	P _{OUT} = +26 dBm, 802.11b, 1 Mbps		-40 -40		dBm/MHz dBm/MHz
Rise and fall time	t _r , t _f				500	μs

¹ Performance is guaranteed only under the conditions listed in this table.

Table 7. SKY85006-11 Electrical Specifications: Logic Characteristics¹
(V_{CC} = 5.0 V, MODE = 0.0 V, EN = V_{ENH}, T_A = 25 °C as Measured on the Evaluation Board (De-Embedded to the Device), All Unused Ports are Terminated with 50 Ω, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Logic voltage:						
High (module on)	V _{ENH}		1.8		3.6	V
Low (module off)	V _{ENL}		0		0.4	
Input current logic voltage:		V _{EN} = 0.4 V				
High	I _{ENH}			1	250	μA
Low	I _{ENL}				20	
Enable pin input impedance	Z _{EN}	Passive pull-down		20		kΩ

¹ Performance is guaranteed only under the conditions listed in this table.

Table 8. SKY85006-11 Electrical Specifications: Logarithmic Power Detector Characteristics¹
(V_{CC} = 5.0 V, MODE = 0.0 V, EN = V_{ENH}, T_A = 25 °C as Measured on the Evaluation Board, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Frequency range	f		2400		2500	MHz
Power detect range	PDR	CW, measured at RF_OUT	+5		+29	dBm
DC source impedance on DET	PDZSRC			2.0		kΩ
DC load impedance	PDZLOAD			1		MΩ
Output voltage	PDV _{DC} PDV _{P5} PDV _{P29}	No RF P _{OUT} = +5 dBm CW P _{OUT} = +29 dBm CW	0.150 0.2 0.775	0.2 0.27 0.850	0.25 0.35 0.925	V
Detector slope	Slope	+5 ≤ P _{OUT} ≤ +29		23		mV/dB
Power detect low-pass filter, -3 dB corner frequency	LPF-3dB			2		MHz

¹ Performance is guaranteed only under the conditions listed in this table.

Evaluation Board Description

The SKY85006-11-EK1 Evaluation Board is used to test the performance of the SKY85006-11 PA. A typical application schematic diagram is provided in Figure 3. Table 9 provides the Bill of Materials (BOM) list for Evaluation Board components. A photograph of the Evaluation Board is shown in Figure 4.

Evaluation Board Test Procedure

1. Connect a spectrum analyzer to the RF signal output port J1.
2. Connect a signal generator to the RF signal input port J3. Set it to the desired RF frequency at a power level of -30 dBm or less to the Evaluation Board.
3. Connect GND to J2 pin 2.
4. Connect 5 V or 3.3 V supply to J2 pin 5.
5. In order to measure the detector voltage, connect a volt meter to J4 pin 1.
6. Connect a +3.3 V supply to J4 pin 6 to enable the PA.
7. Take measurements.

CAUTION: *If the input signal exceeds the rated power, the Evaluation Board can be permanently damaged.*

NOTE: *It is important to adjust the VCC voltage source so that the target supply voltage (+5 or +3.3) is measured at the board. The high collector currents will drop the collector voltage significantly if long leads are used. Adjust the bias voltage to compensate.*

Circuit Design Considerations

The following design considerations are general in nature and must be followed regardless of final use or configuration:

- Paths to ground should be made as short as possible.
- The ground pad of the SKY85006-11 has special electrical and thermal grounding requirements. This pad is the main thermal conduit for heat dissipation. Since the circuit board acts as the heat sink, it must shunt as much heat as possible from the device.

Therefore, design the connection to the ground pad to dissipate the maximum wattage produced by the circuit board. Multiple vias to the grounding layer are required.

For further information, refer to the Skyworks Application Note, *PCB Design Guidelines for High Power Dissipation Packages*, document number 201211.

- Bypass capacitors should be used on the DC supply lines. An RF inductor is required on the VCC supply line to block RF signals from the DC supply. Refer to the schematic drawing in Figure 4 for further details.
- The RF lines should be well separated from each other with solid ground in between traces to maximize input-to-output isolation.

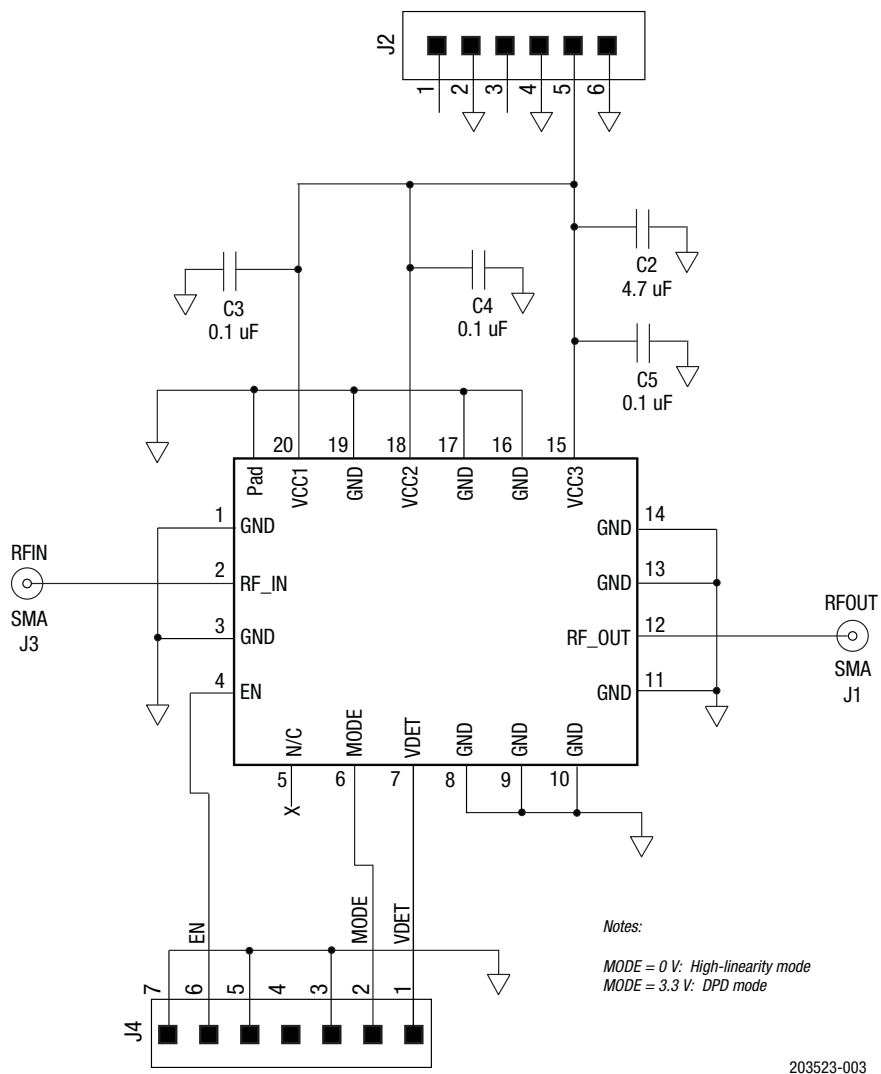


Figure 3. SKY85006-11 Evaluation Board Schematic Diagram

Table 9. SKY85006-11 Evaluation Board Bill of Materials

Component	Value	Manufacturer	Mfr Part Number	Package	Description
C2	4.7uF	Murata	GRM188R60J475KE190	0603	Ceramic capacitor, 4.7 uF, 10%, X5R, 16 V,
C3, C4, C5	0.1 uF	Taio Yuden	EM105B7104KV	0402	Ceramic capacitor, 0.1 uF, 10%, X7R, 16 V, (RSI)

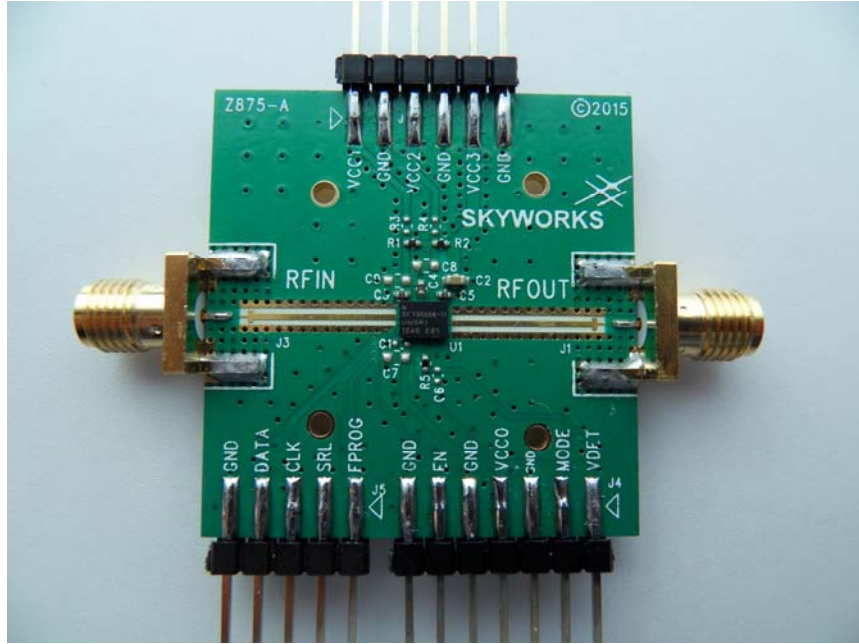


Figure 4. SKY85006-11 Evaluation Board

Package Dimensions

Typical part markings for the SKY85006-11 are shown in Figure 5. The PCB layout footprint for the SKY85006-11 is provided in Figure 6. Package dimensions are shown in Figure 7, and tape and reel dimensions are provided in Figure 8.

Package and Handling Information

Since the device package is sensitive to moisture absorption, it is baked and vacuum packed before shipping. Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY85006-11 is rated to Moisture Sensitivity Level 3 (MSL3) at 260 °C, and can be used for lead or lead-free soldering. For additional information, refer to the Skyworks Application Note, *Solder Reflow Information* (Document Number 200164).

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format.

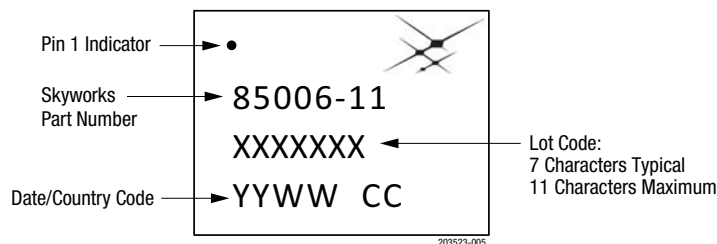
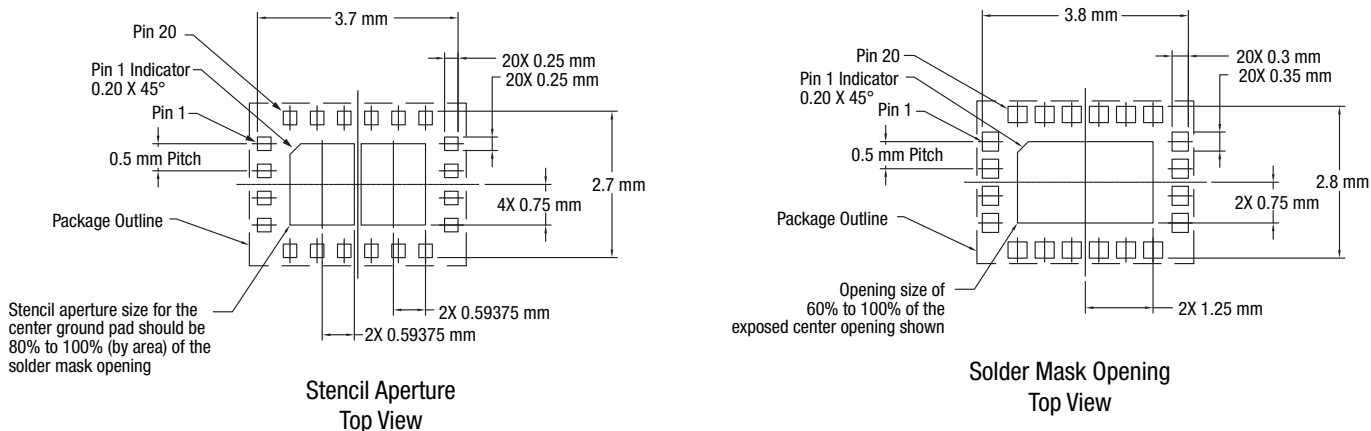


Figure 5. SKY85006-11 Typical Part Markings (Top View)



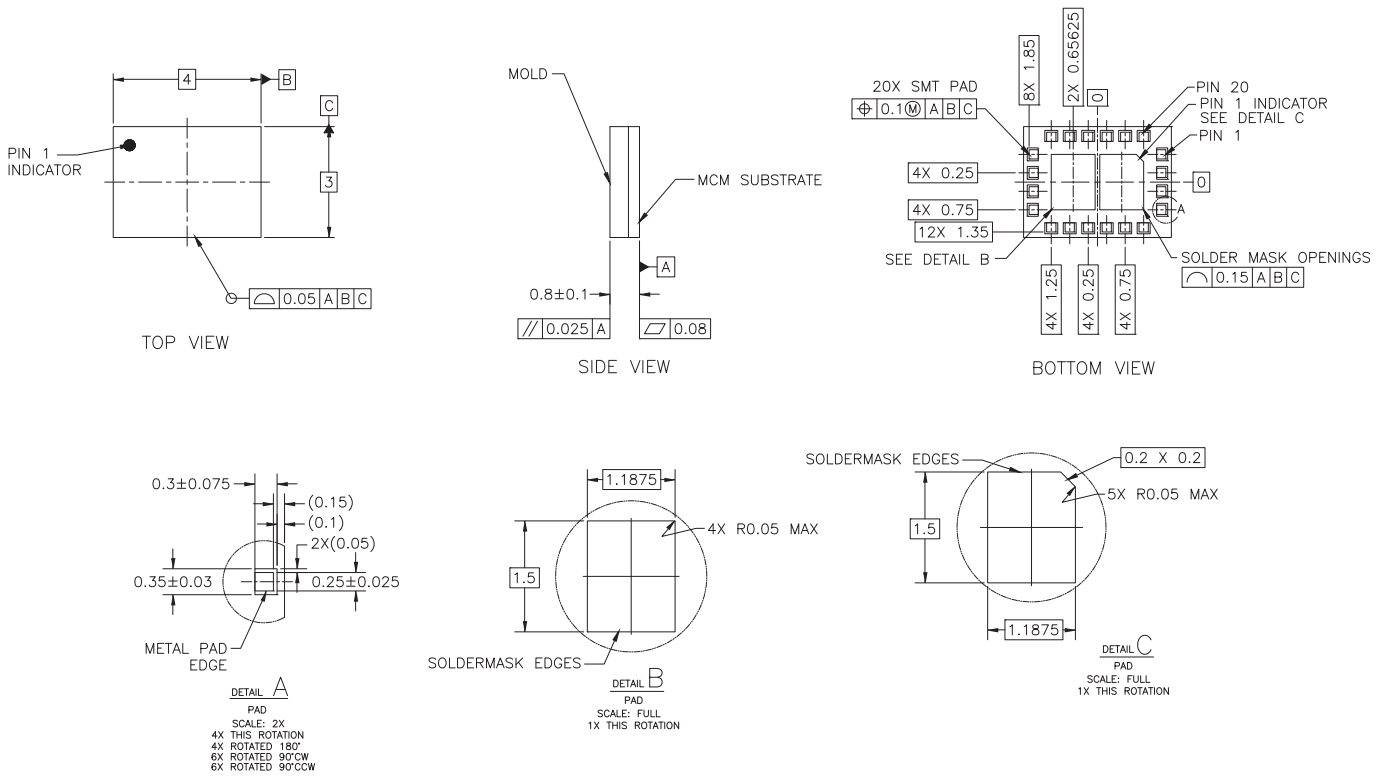
Notes:

1. Thermal vias should be resin filled and capped in accordance with IPC-4761 Type VII vias.
2. Recommended Cu thickness is 30 to 35 μm.

203523-006

Figure 6. SKY85006-11 PCB Layout Footprint

DATA SHEET • SKY85006-11: 2.4 GHz HIGH-POWER WIRELESS LAN POWER AMPLIFIER



NOTES: UNLESS OTHERWISE SPECIFIED.

1. DIMENSIONING AND TOLERANCING IN ACCORDANCE WITH ASME Y14.5M-1994.
2. SEE APPLICABLE BONDING DIAGRAM AND DEVICE ASSEMBLY DRAWING FOR DIE AND COMPONENT PLACEMENT.
3. PAD DEFINITIONS PER DETAILS ON DRAWING.
4. PCB TYPE 5L NS SSV 250 MCM (CORELESS).
5. THIS PACKAGE USES CONFORMAL SHIELDING.

203523-007

Figure 7. SKY85006-11 Package Dimensions

Ordering Information

Product Description	Product Part Number	Evaluation Board Part Number
SKY85006-11: 2.4 GHz High Power Wireless LAN PA	SKY85006-11	SKY85006-11EK1

Copyright © 2015-2018 Skyworks Solutions, Inc. All Rights Reserved.

Information in this document is provided in connection with Skyworks Solutions, Inc. ("Skyworks") products or services. These materials, including the information contained herein, are provided by Skyworks as a service to its customers and may be used for informational purposes only by the customer. Skyworks assumes no responsibility for errors or omissions in these materials or the information contained herein. Skyworks may change its documentation, products, services, specifications or product descriptions at any time, without notice. Skyworks makes no commitment to update the materials or information and shall have no responsibility whatsoever for conflicts, incompatibilities, or other difficulties arising from any future changes.

No license, whether express, implied, by estoppel or otherwise, is granted to any intellectual property rights by this document. Skyworks assumes no liability for any materials, products or information provided hereunder, including the sale, distribution, reproduction or use of Skyworks products, information or materials, except as may be provided in Skyworks Terms and Conditions of Sale.

THE MATERIALS, PRODUCTS AND INFORMATION ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, WHETHER EXPRESS, IMPLIED, STATUTORY, OR OTHERWISE, INCLUDING FITNESS FOR A PARTICULAR PURPOSE OR USE, MERCHANTABILITY, PERFORMANCE, QUALITY OR NON-INFRINGEMENT OF ANY INTELLECTUAL PROPERTY RIGHT; ALL SUCH WARRANTIES ARE HEREBY EXPRESSLY DISCLAIMED. SKYWORKS DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. SKYWORKS SHALL NOT BE LIABLE FOR ANY DAMAGES, INCLUDING BUT NOT LIMITED TO ANY SPECIAL, INDIRECT, INCIDENTAL, STATUTORY, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS THAT MAY RESULT FROM THE USE OF THE MATERIALS OR INFORMATION, WHETHER OR NOT THE RECIPIENT OF MATERIALS HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

Skyworks products are not intended for use in medical, lifesaving or life-sustaining applications, or other equipment in which the failure of the Skyworks products could lead to personal injury, death, physical or environmental damage. Skyworks customers using or selling Skyworks products for use in such applications do so at their own risk and agree to fully indemnify Skyworks for any damages resulting from such improper use or sale.

Customers are responsible for their products and applications using Skyworks products, which may deviate from published specifications as a result of design defects, errors, or operation of products outside of published parameters or design specifications. Customers should include design and operating safeguards to minimize these and other risks. Skyworks assumes no liability for applications assistance, customer product design, or damage to any equipment resulting from the use of Skyworks products outside of stated published specifications or parameters.

Skyworks and the Skyworks symbol are trademarks or registered trademarks of Skyworks Solutions, Inc. or its subsidiaries in the United States and other countries. Third-party brands and names are for identification purposes only, and are the property of their respective owners. Additional information, including relevant terms and conditions, posted at www.skyworksinc.com, are incorporated by reference.